

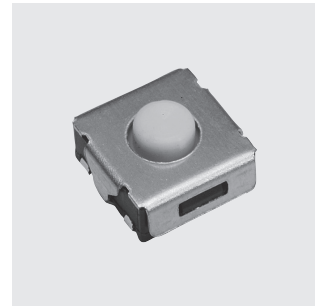


**THE DATASHEET OF
SMTE3-01E-Z**



SMT3/SMTE3

Surface Mount Tactile Switches



Washable

RoHS Compliant

■ Features

- 1. Compatible With Lead-Free, Reflow Soldering**
Heat-resistance resin for lead-free soldering.
- 2. Washable (SMTE3 Series)**
- 3. J-Lead Terminal Pins For High-Density Mounting**
- 4. Anti-Static Electricity (SMTE3 Series)**
Ground terminal is provided to prevent damage to element caused by static electricity.

■ Specifications

Rating	Max.	0.6VA max. (24VDC max. 30mA max.)	
	Min.	Silver plated contacts	1mA 5VDC
		Gold plated contacts	10μA 5VDC
Initial contact resistance	100mΩ max. (1.5mA 200μVAC)		
Dielectric strength	250VAC 1 minute		
Insulation resistance	100MΩ min. (100VDC)		
Electrostatic capacity	5pF max.		
Electrical life	100,000 operations		
Stroke	SMT3	0.25mm	
	SMTE3	0.5mm	
Operating force	SMT3	1.18±0.39 N	
	SMTE3	1.96±0.98 N	
Operating temperature range	-25~+70°C		
Storage temperature range	-40~+85°C		

■ Part Numbering

SMT E G 3 - 01 E - Z

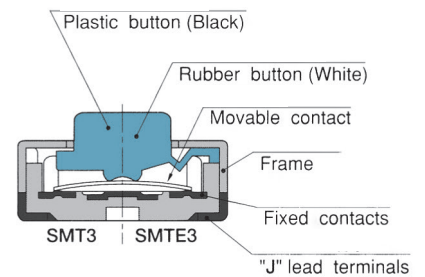
Series code Structure Contact plating Series No. Registration No. Packaging specs.

None	Standard type (Plastic button)
E	Immersion washable (Rubber button)

None	Silver plated
G	Gold plated

None	Stick
E	Emboss taping

■ Structure



■ Table of Part Numbers

Structure	Packaging specifications	
	Stick	Emboss taping
Standard type	SMT3-01-Z	SMT3-01E-Z ★ SMTG3-01E-Z
Immersion washable	SMTE3-01-Z ★ SMTEG3-01-Z	SMTE3-01E-Z ★ SMTEG3-01E-Z

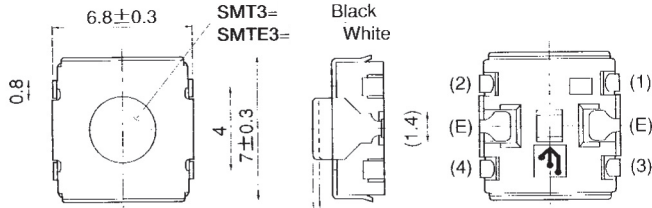
■ Pad Layouts

(Top view)

Ground terminals	Without	With
Part No.	SMT3 • SMTE3 SMTG3 • SMTEG3	SMTE3 SMTEG3
Pattern dimensions		

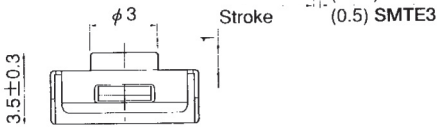
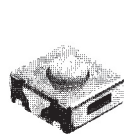
■ SPST

SMT3



SMTE3

Washable



Terminal numbers are not shown on the switch.

Part No.	Switching function	
SMT3-01-Z SMT3-01E-Z SMTG3-01E-Z SMTE3-01-Z SMTE3-01E-Z SMTEG3-01-Z SMTEG3-01E-Z	OFF	(ON)
Connecting terminals	—	1 — 3 2 — 4
Circuit diagrams		

(ON) : Momentary

(E) : GGround terminal (SMTE3 and SMTEG3 series)

■ Soldering Specifications

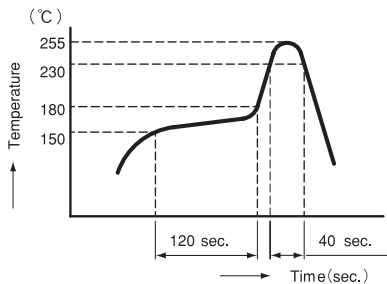
(1) Manual Soldering

Device : Soldering iron

① 350°C ± 10°C; 3 ± 0.5 seconds

(2) Reflow Soldering

Device : Inline or batch system



• Apply reflow soldering up to 2 times max.

■ Flux Cleaning

Since the **SMT3** series is not process sealed, be sure to use low-residue flux.

(1) Solvent: Fluorine or Alcohol type Cleaning with other solvents or water is not possible.

(2) Cleaning after soldering should be done after the terminal temperature falls to 90°C or below, or after leaving the switch for five minutes or longer at room temperature.

Cleaning temperature: 43°C, max.

(3) Do not use ultrasonic cleaning.

■ Packaging Specifications

Stick	Emboss taping
50 pcs/stick	1,000 pcs/reel
Q=375	

● When ordering, tape packaged version shall be supplied by request. Minimum packaging quantity for reel packaging is 1,000pcs per reel.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

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- ⊖ [Copal Electronics Inc. Information](#)

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- ✓ Shortage Management
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